

Notice of References Cited

Application/Control No.

09/920,034

Applicant(s)/Patent Under
Reexamination
CHIEN ET AL.

Examiner

Russell Frejd

Art Unit

2128

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*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
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	C	US-6,442,496	08-2002	Pasadyn et al.	702/83
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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.

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